

**WNMD2182**
**Dual N-Channel, 20V, 9.5A, Power MOSFET**
[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

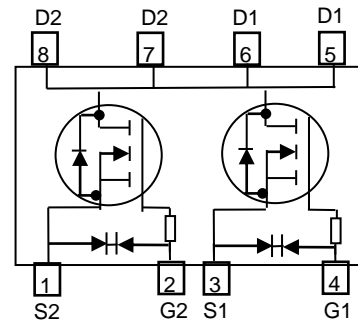
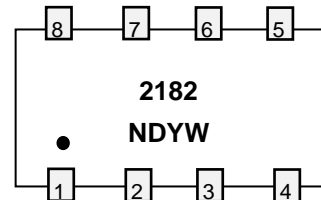
V <sub>DS</sub> (V)	R <sub>ds(on)</sub> (mΩ)
20	12 @ V <sub>GS</sub> =4.5V
	14 @ V <sub>GS</sub> =3.1V
	17 @ V <sub>GS</sub> =2.5V
ESD HBM 2000V	



PDFN2.9x2.8-8L

**Descriptions**

The WNMD2182 is Dual N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent R<sub>DS (ON)</sub> with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WNMD2182 is Pb-free and Halogen-free.


**Pin configuration (Top view)**


2182 = Device Code  
 ND = Special Code  
 YW = Year & Week

**Marking**
**Features**

- Trench Technology
- Supper high density cell design
- Excellent ON resistance for higher DC current
- Extremely Low Threshold Voltage
- Small package PDFN2.9x2.8-8L
- ESD Protected Class-2 (HBM 2000V)

**Applications**

- Driver for Relay, Solenoid, Motor, LED etc.
- DC-DC converter circuit
- Power Switch
- Load Switch
- Charging

**Order information**

Device	Package	Shipping
WNMD2182-8/TR	PDFN2.9×2.8-8L	3000/Reel&Tape

**Absolute Maximum ratings**

Parameter	Symbol	10 S	Steady State	Unit	
Drain-Source Voltage	$V_{DS}$	20		V	
Gate-Source Voltage	$V_{GS}$	$\pm 10$			
Continuous Drain Current <sup>a,e</sup>	$I_D$	$T_A=25^\circ\text{C}$	9.5	7.1	A
		$T_A=70^\circ\text{C}$	7.6	5.7	
Maximum Power Dissipation <sup>a</sup>	$P_D$	$T_A=25^\circ\text{C}$	1.7	0.9	W
		$T_A=70^\circ\text{C}$	1.1	0.6	
Continuous Drain Current <sup>b,e</sup>	$I_D$	$T_A=25^\circ\text{C}$	9.3	6.6	A
		$T_A=70^\circ\text{C}$	7.4	5.3	
Maximum Power Dissipation <sup>b</sup>	$P_D$	$T_A=25^\circ\text{C}$	1.6	0.8	W
		$T_A=70^\circ\text{C}$	1.0	0.5	
Pulsed Drain Current <sup>c</sup>	$I_{DM}$	38		A	
Operating Junction Temperature	$T_J$	-55~+150		$^\circ\text{C}$	
Lead Temperature	$T_L$	260		$^\circ\text{C}$	
Storage Temperature Range	$T_{stg}$	-55 to 150		$^\circ\text{C}$	

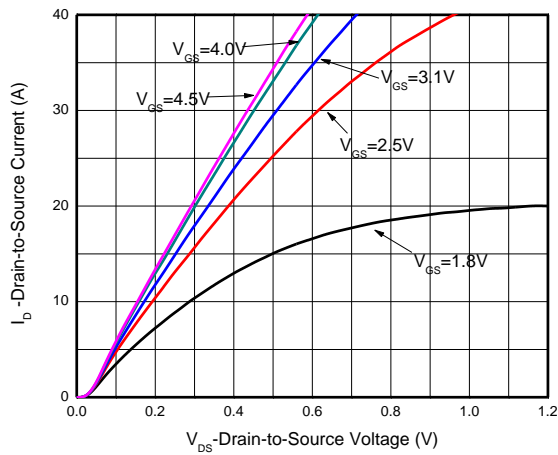
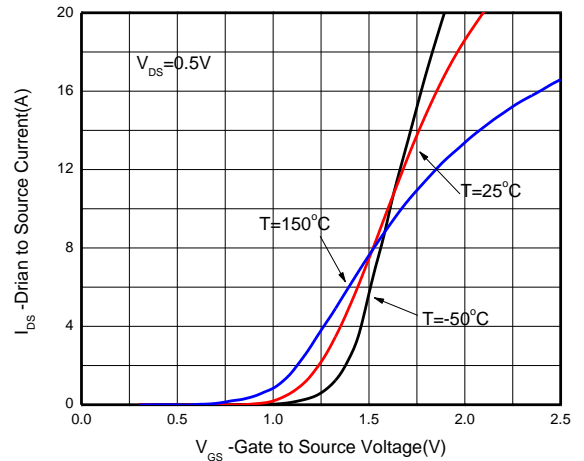
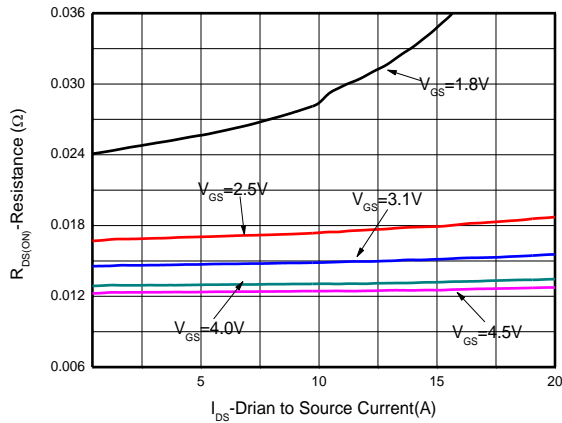
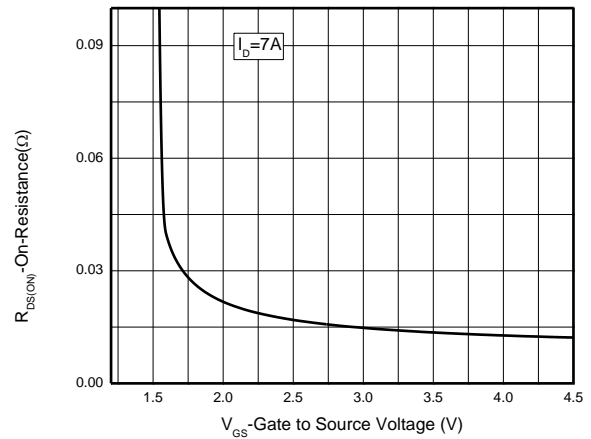
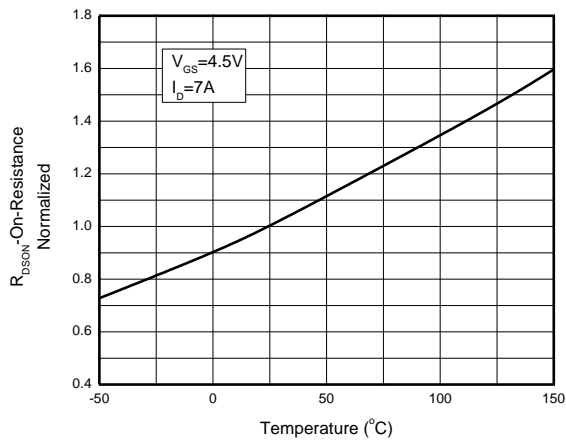
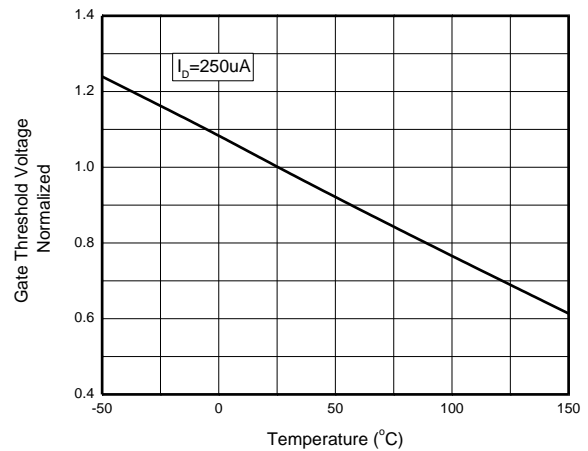
**Thermal resistance ratings**

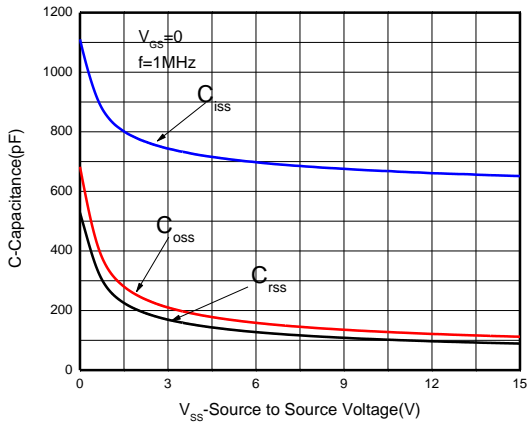
Single Operation					
Parameter	Symbol	Typical	Maximum	Unit	
Junction-to-Ambient Thermal Resistance <sup>a</sup>	$R_{\theta JA}$	$t \leq 10 \text{ s}$	61	72	$^\circ\text{C/W}$
		Steady State	102	128	
Junction-to-Ambient Thermal Resistance <sup>b</sup>	$R_{\theta JA}$	$t \leq 10 \text{ s}$	65	75	
		Steady State	120	148	
Junction-to-Case Thermal Resistance	$R_{\theta JC}$	54	63		

- a Surface mounted on FR-4 Board using 1 square inch pad size, 1oz copper;.
- b Surface mounted on FR-4 board using minimum pad size, 1oz copper;.
- c Pulse width<380 $\mu\text{s}$ , Duty Cycle<2%;.
- d Maximum junction temperature  $T_J=150^\circ\text{C}$ ;
- e Current rating is limited by wire-bonding.

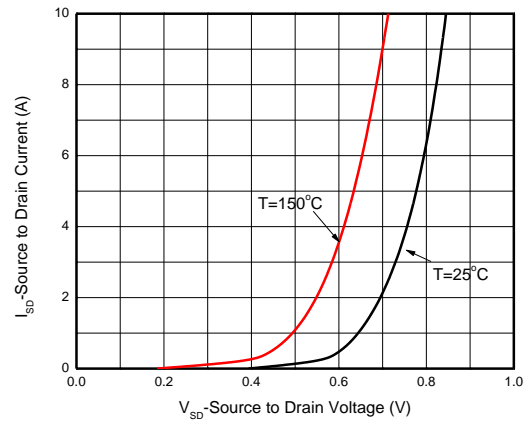
**Electronics Characteristics (Ta=25°C, unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250uA	20			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 16 V, V <sub>GS</sub> = 0V			1	uA
Gate-to-source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±10V			±5	uA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 250uA	0.4	0.65	1.0	V
Drain-to-source On-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 6.5A	8	12	17	mΩ
		V <sub>GS</sub> = 3.1V, I <sub>D</sub> = 5.5A	10	14	20	
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 3.0A	12	17	30	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> = 5.0 V, I <sub>D</sub> = 4.8A		17		S
<b>CHARGES, CAPACITANCES AND GATE RESISTANCE</b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1.0 MHz, V <sub>DS</sub> = 10 V		670		pF
Output Capacitance	C <sub>OSS</sub>			130		
Reverse Transfer Capacitance	C <sub>RSS</sub>			103		
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 4.5 V, V <sub>DD</sub> = 10 V, I <sub>D</sub> = 7A		10		nC
Threshold Gate Charge	Q <sub>G(TH)</sub>			0.7		
Gate-to-Source Charge	Q <sub>GS</sub>			1.5		
Gate-to-Drain Charge	Q <sub>GD</sub>			3		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	td(ON)	V <sub>GS</sub> = 4.5 V, V <sub>DD</sub> = 6 V, I <sub>D</sub> = 4.8A, R <sub>G</sub> = 6 Ω		26		ns
Rise Time	tr			48.8		
Turn-Off Delay Time	td(OFF)			189.6		
Fall Time	tf			135		
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 1.0A		0.7	1.5	V

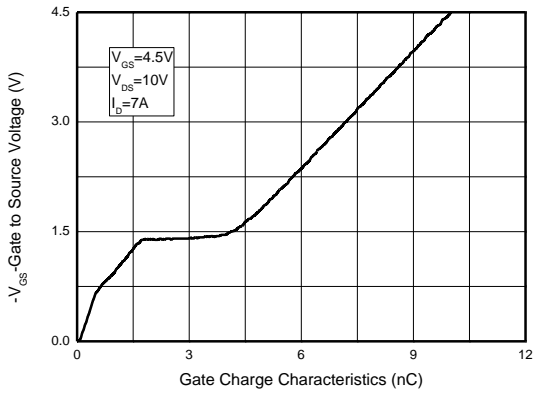
**Typical Characteristics (Ta=25°C, unless otherwise noted)**

**Output characteristics**

**Transfer characteristics**

**On-Resistance vs. Drain current**

**On-Resistance vs. Gate-to-Source voltage**

**On-Resistance vs. Junction temperature**

**Threshold voltage vs. Temperature**



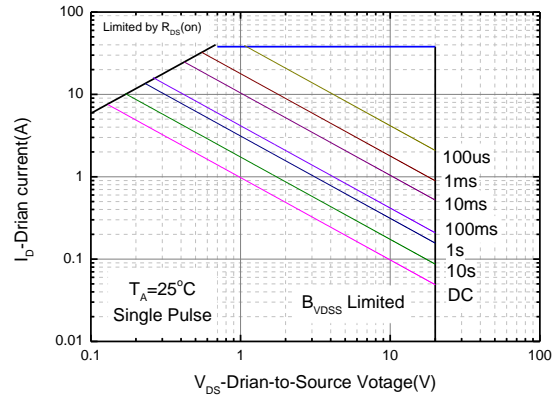
Capacitance



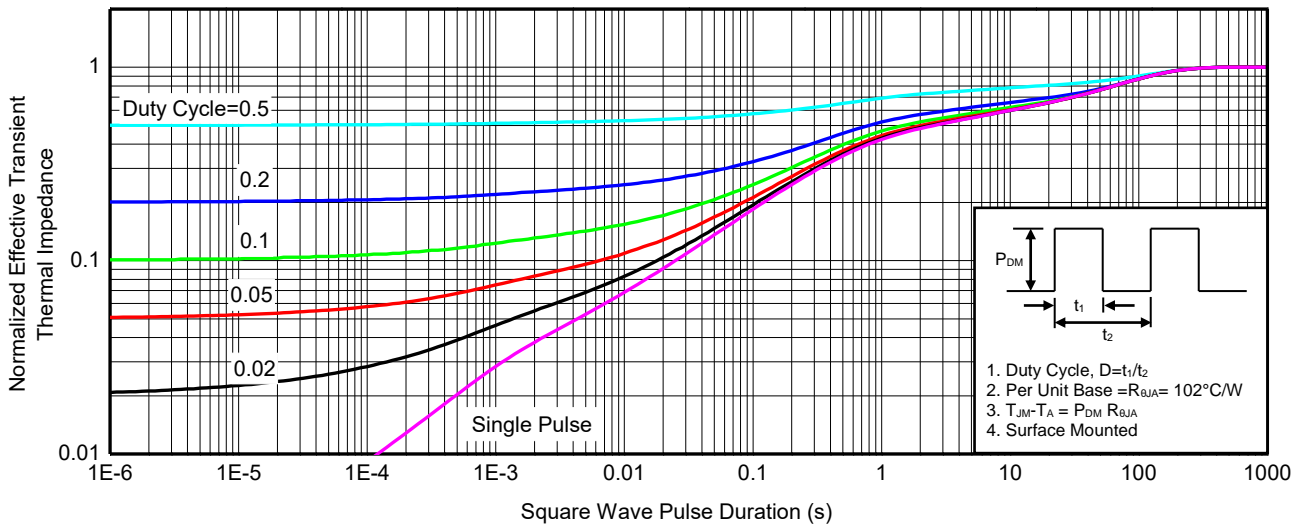
Body diode forward voltage



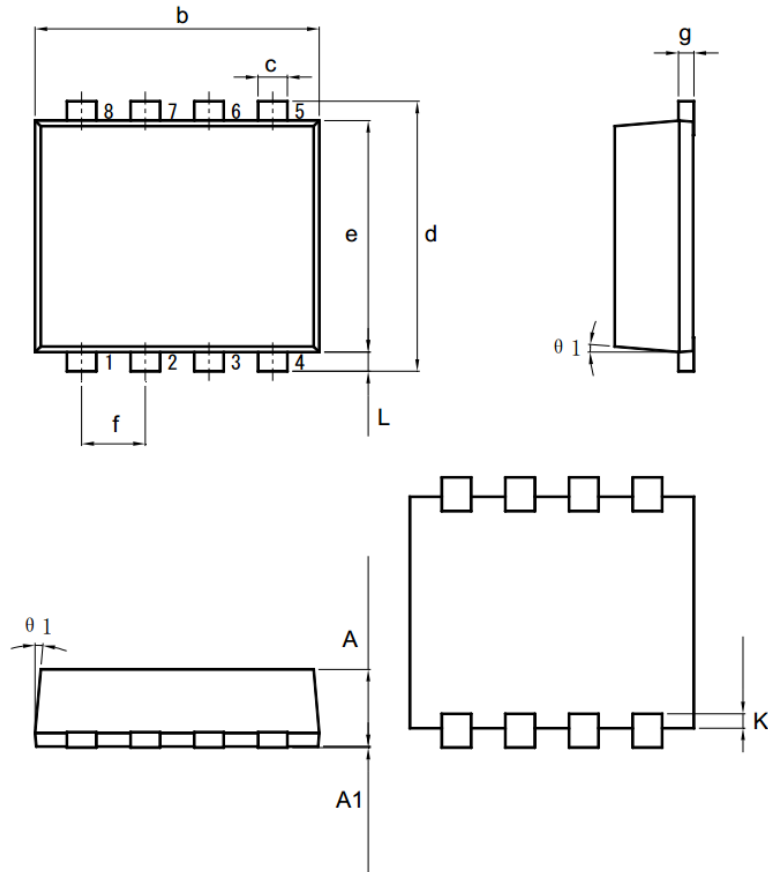
Gate Charge Characteristics



Safe operating power



Transient thermal response (Junction-to-Ambient)

**Package outline dimensions**
**PDFN2.9\*2.8-8L**


Symbol	Dimensions in millimeter		
	Min.	Typ.	Max.
A	0.750	0.800	0.850
A1	0.000	—	0.020
b	2.800	2.900	3.000
c	0.250	0.300	0.400
d	2.700	2.800	2.900
e	2.300	2.400	2.500
f	0.650		
g	0.110	0.160	0.260
L	0.200		
K	0.150		
theta 1	5°		